CMP PAD CONDITIONER, PAD CONDITIONING SYSTEM AND METHOD

ABSTRACT

A chemical mechanical planarization (CMP) pad conditioner, a CMP pad conditioning system and a CMP pad conditioning method are provided. The CMP pad conditioner includes an adaptor configured to receive an abrasive member and a sensing circuit comprising one or more sensing elements. Each of the one or more sensing elements is configured to measure a respective parameter associated with the abrasive member.

FIG. 1a